

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled: **A Semiconductor Substrate with Solid Phase epitaxial regrowth with reduced junction leakage and method of producing same**
the specification of which (check only one item below):

☐ is attached hereto.

☐ was filed as United States application

Serial No

on

and was amended

on

☒ was filed as PCT international application

Number **1B 2004 / 052644**

on **2 December 2004**

and was amended under PCT Article 19

on (if applicable).



I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s) for patent or inventor's certificate or of any PCT international application(s) designating at least one country other than the United States of America listed below and have identified below any foreign application(s) for patent or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America filed by me on the same subject matter having a filing date before that of the application(s) of which priority is claimed:

PRIOR FOREIGN/PCT APPLICATION(S) AND ANY PRIORITY CLAIMS UNDER 35 U.S.C. 119:

COUNTRY	APPLICATION NUMBER	DATE OF FILING DAY, MONTH, YEAR	PRIORITY CLAIMED UNDER 35 USC 119
Europe	03104781.4	18 December 2003	YES

ombined Declaration For Patent Application and Power of Attorney (Continued) (includes Reference to PCT International Applications)				Attorneys Docket Number PHNL031498 US
POWER OF ATTORNEY: As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith. (List name and registration number)				
Jack E. Haken, Reg. No. 26,902 Michael E. Marion, Reg. No. 32, 266 Edward M. Blocker, Reg. No. 30,245				Direct Telephone Calls to: (name and telephone number) (914)332-0222
201	FULL NAME OF INVENTOR	FAMILY NAME PAWLAK	FIRST GIVEN NAME Bartlomiej	SECOND GIVEN NAME Jan
	RESIDENCE & CITIZENSHIP	CITY Leuven	STATE OR FOREIGN COUNTRY Belgium	COUNTRY OF CITIZENSHIP Poland
	POST OFFICE ADDRESS	POST OFFICE ADDRESS Kapeldreef 75	CITY B-3001 Leuven	STATE & ZIP CODE/COUNTRY Belgium
202	FULL NAME OF INVENTOR	FAMILY NAME DUFFY	FIRST GIVEN NAME Raymond	SECOND GIVEN NAME James
	RESIDENCE & CITIZENSHIP	CITY Leuven	STATE OR FOREIGN COUNTRY Belgium	COUNTRY OF CITIZENSHIP Ireland
	POST OFFICE ADDRESS	POST OFFICE ADDRESS Kapeldreef 75	CITY B-3001 Leuven	STATE & ZIP CODE/COUNTRY Belgium
203	FULL NAME OF INVENTOR	FAMILY NAME LINDSAY	FIRST GIVEN NAME Richard	SECOND GIVEN NAME
	RESIDENCE & CITIZENSHIP	CITY Leuven	STATE OR FOREIGN COUNTRY Belgium	COUNTRY OF CITIZENSHIP Great Britain
	POST OFFICE ADDRESS	POST OFFICE ADDRESS Kapeldreef 75	CITY B-3001 Leuven	STATE & ZIP CODE/COUNTRY Belgium
I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under section 1001 if Title 18 of the United states Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.				
SIGNATURE OF INVENTOR 201 		SIGNATURE OF INVENTOR 202 		SIGNATURE OF INVENTOR 203
DATE 25.4.06.		DATE 25.4.06.		DATE

U.S. DEPARTMENT OF COMMERCE- Patent and Trademarks Office

(July 1994)

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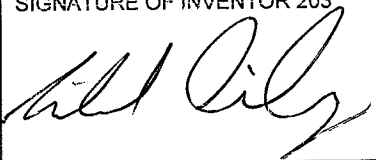
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